

FYLS-3528UWC

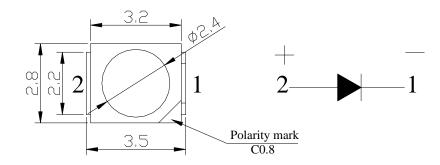
Features:

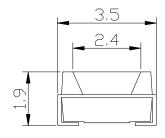
- Chips can be controlled separately.
- Suitable for all SMT Assembly and solder process.
- Available on tape and Reel
- Package :2000pcs/ Reel

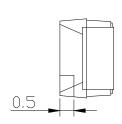
Description.

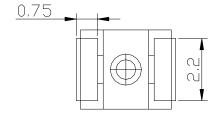
 The White source color devices are made with Gallium arsenide Phosphide on Gallium Phosphide White light Emitting Diode.

Package Dimensions









Notes:

- 1. All dimension units are millimeters (Inches)
- 2. All dimension tolerance ±0.2mm unless otherwise noted.
- 3. An epoxy meniscus may extend about 1.5mm down the leads.



Selection Guide

Part No.	Dice	lens type	IV(mcd)@20mA		Viewing Angle
			Min	Тур	2θ _{1/2}
FYLS-3528UWC	White(InGaN)	Yellow Diffused	1300	2000	120

Electrical/Optical Characteristics at Ta=25 °c

Symbol	Parameter	Device	min.	typ.	units	test conditions
VF	Forward Voltage	White	3.0	3.2	V	IF=20mA
IR	Reverse Current	-		5	μΑ	VR=5V
Х	Chromaticity	_		0.33		
Υ	Coordinates			0.33		
Color Temperature	ССТ		5000	7000	К	IF=20mA
Luminous Flux	Φν			6.5	lm	

Absolute Maximum Ratings At= 25 °c

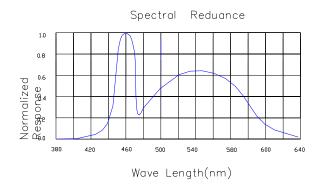
Parameter	White	Units	
Power dissipation	114	mW	
DC Forward Current	30	mA	
Peak Forward Current(1)	150	mA	
Reverse Voltage	5	V	
Operating/storage Temperature	-40℃ to +85℃		

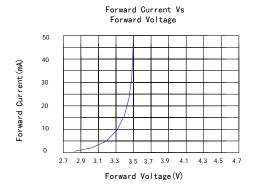
Note:

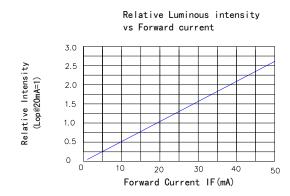
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

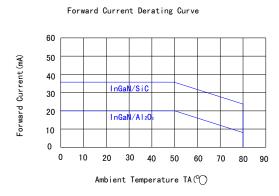


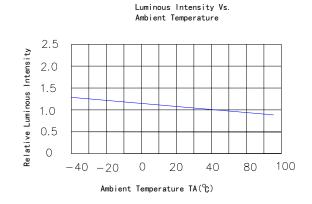
Typical Electrical/Optical Characteristics Curves (Ta=25 ℃ Unless Otherwise Noted)







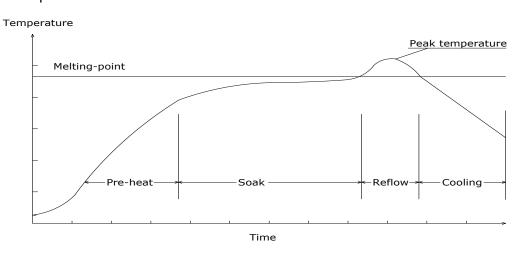






Precautions for use:

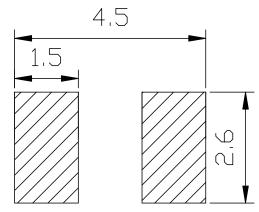
- 1. Suggest the LEDs should be kept between 5°C and 30°C and 60%RH or less before opening the package, The max. storage period before opening the package is 1 year.
- 2. After opening the package, the LEDs should be kept at 30°C/35%RH or less, and it should be used within 1 hours. In the event of incomplete usage, it is advised that user preheat the remaining devices at 60±5°C for 12 hours prior to use.
- 3. The temperature of manual of soldering not more then 300°C within 2 sec. The temperature of Reflow soldering not more then 260°C within 2 sec, should not be done more than twice. When soldering, don't tress on LEDs during heating. After soldering, don't warp the circuit board.
- 4. Repair should not be done after the LEDs have been soldered. When repair is unavoidable, Double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will be damaged by repair or not.
- (1) Reflow soldering Temperature profile



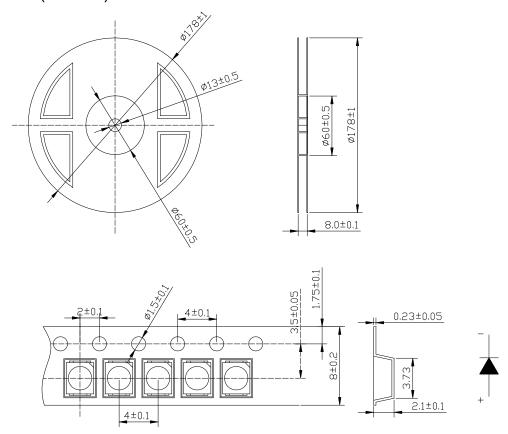
Solder=Sn63-Pb37	Solder= Pb-Free	
Average ramp-up rate:4℃/sec.max	Average ramp-up rate:4°C/sec.max	
Peak preheat temperature:100-150℃	Peak preheat temperature:100-150℃	
preheat time:100seconds.max	preheat time:100seconds.max	
ramp-down rate:6℃/sec.max	ramp-down rate:6℃/sec.max	
Peak temperature:230°C	Peak temperature:250°C	
Time within 5° C of actual peak	Time within 5℃ of actual peak temperature=10	
temperature=10 sec. max	sec. max	
Duration above $183^^$ is 80 sec. max	Duration above 217℃ is 80 sec. max	

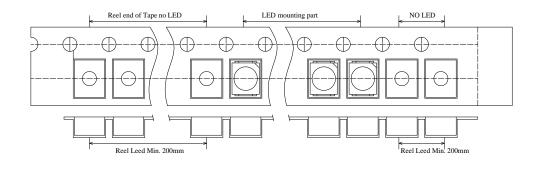


Recommended Soldering Pattern(Unit:mm)



Taping Dimension (Unit:mm)







◆ Packing and Shipping Spec.

